Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-08-24
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Laurent TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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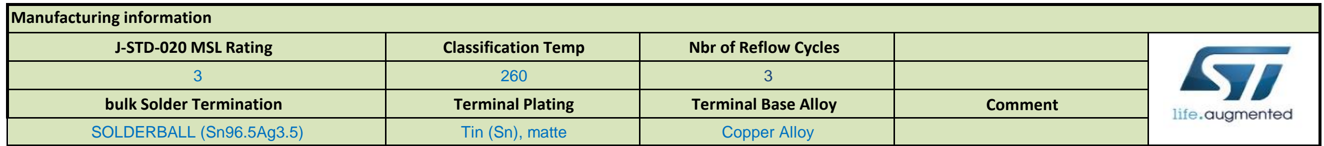
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F767IIK6	P0MR*451XXXZ	A	9996	2018-08-24
	Amount	UoM	Unit type	ST ECOPACK Grade
	140.37	mg	Each	ECOPACK® 2
,	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant		



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SOLDERBALL (Sn96.5Ag3.5)	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	10x10x0.6	176+25	No lead	
Comment	Package: A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**true**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**

QueryList : REACH-12th January 2017	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	P0MR*451XXXZ					
Homogeneous Material	**Material Group**	Mass	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	7.551	mg	supplier	die	Silicon (Si)	7440-21-3		5.969	mg	790491	42523
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.111	mg	14700	791
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.719	mg	95219	5122
Die				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	265	14
Die				supplier	metallization	Tantalum (Ta)	7440-25-7		0.100	mg	13243	712
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.323	mg	42776	2301
Die				supplier	Passivation	Silicon Nitride	12033-89-5		0.084	mg	11124	598
Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.243	mg	32181	1731
SUBSTRATE (DS-7409HGB) Core	Other inorganic materials	41.000	mg	supplier	CORE	Organic resin	Trade secret		9.430	mg	230000	67180
SUBSTRATE (DS-7409HGB) Core				supplier	CORE	Other inorganic filler	Trade secret		10.660	mg	260000	75942
SUBSTRATE (DS-7409HGB) Core				supplier	CORE	Glass fiber	65997-17-3		20.910	mg	510000	148963
SUBSTRATE (DS-7409HGB) Solder Mask	Other inorganic materials	10.008	mg	supplier	SOLDERMASK	Organic resin	Trade secret		6.505	mg	650000	46341
SUBSTRATE (DS-7409HGB) Solder Mask				supplier	SOLDERMASK	Inorganic filler	Trade secret		3.503	mg	350000	24953
SUBSTRATE (DS-7409HGB) Cu	Other inorganic materials	11.544	mg	supplier	CU FOIL	Copper (Cu)	7440-50-8		11.544	mg	1000000	82239
SUBSTRATE (DS-7409HGB) Ni	Other inorganic materials	3.821	mg	supplier	NI PLATING	Nickel (Ni)	7440-02-0		3.821	mg	1000000	27219
SUBSTRATE (DS-7409HGB) Au	Other inorganic materials	0.638	mg	supplier	AU PLATING	Gold (Au)	7440-56-7		0.638	mg	1000000	4542
DIE ATTACH (ATB-130U)	Other inorganic materials	0.972	mg	supplier	GLUE	Epoxy resin	Trade secret		0.953	mg	980039	6786
DIE ATTACH (ATB-130U)				supplier	GLUE	Filler	Trade secret		0.019	mg	19961	138
BONDING WIRE (MKE 4N)	Other inorganic materials	2.706	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		2.706	mg	1000000	19279
SOLDERBALL (Sn96.5Ag3.5)	Other inorganic materials	6.241	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		6.023	mg	965007	42907
SOLDERBALL (Sn96.5Ag3.5)				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.218	mg	34993	1556
ENCAPSULATION (GE-100LFCS)	Other inorganic materials	55.890	mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		48.955	mg	875914	348757
ENCAPSULATION (GE-100LFCS)				supplier	MOLDING COMPOUND	Epoxy resin	Trade secret		6.935	mg	124086	49407